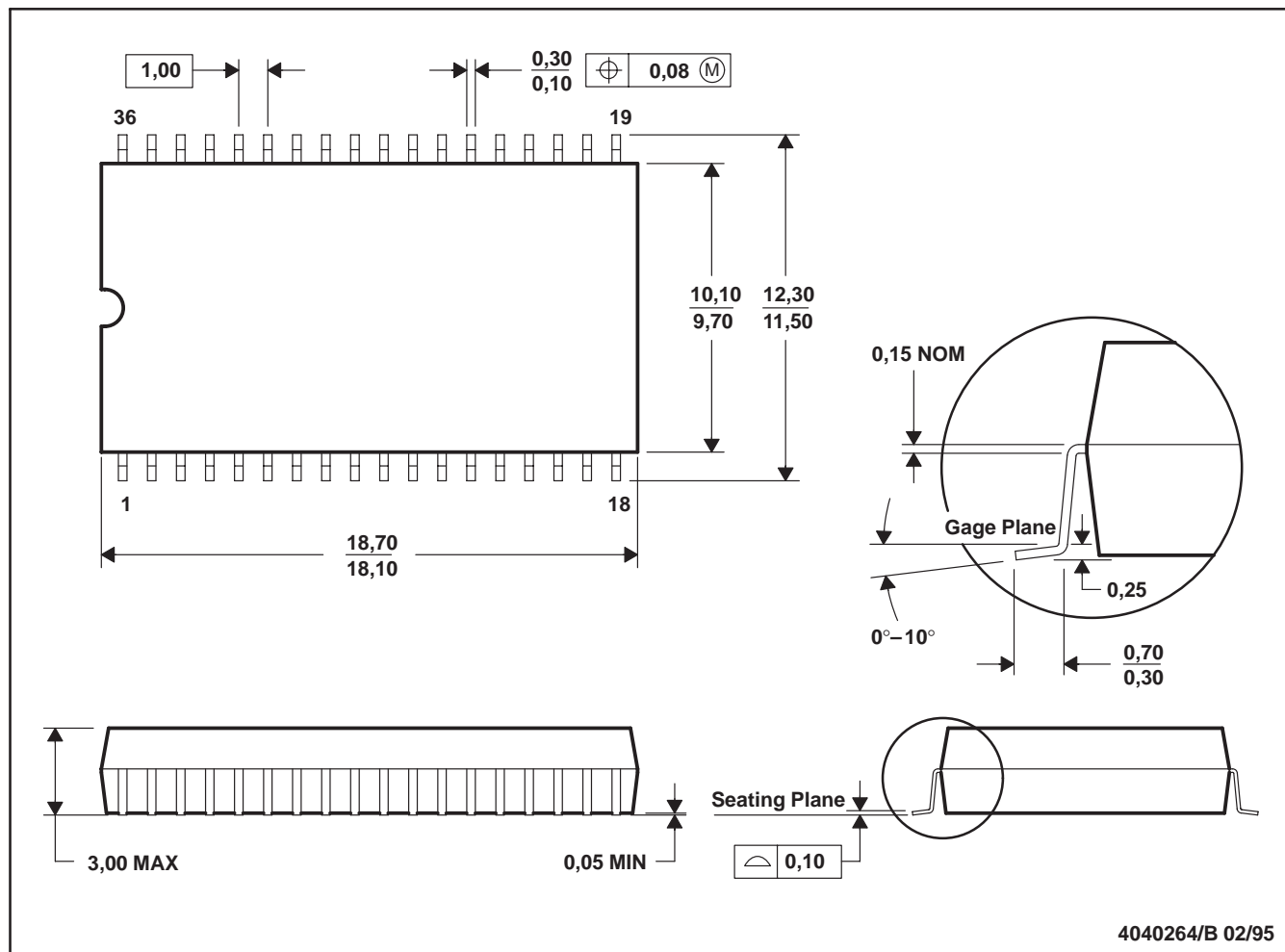


DT (R-PDSO-G36)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.

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